

**DDR4 DIMM**

TE Internal #: 2309409-2

DDR4 DIMM, SO DIMM Sockets, Small Outline (SO), Stack Height .205 in [5.2 mm], Right Angle Module Orientation, Surface Mount, Cable-to-Board

[View on TE.com >](#)
[Connectors > Socket Connectors > Memory Sockets > SO DIMM Sockets > DDR4 SO DIMM SOCKETS](#)
DRAM Type: **Small Outline (SO)**Stack Height: **5.2 mm [.205 in]**Module Orientation: **Right Angle**PCB Mounting Style: **Surface Mount**Connector System: **Cable-to-Board**
[All DDR4 SO DIMM SOCKETS \(39\)](#)
Features**Product Type Features**

| | |
|-----------------------------------|-----------------------|
| Center Post | Without |
| DRAM Type | Small Outline (SO) |
| Connector System | Cable-to-Board |
| Sealable | No |
| Connector & Contact Terminates To | Printed Circuit Board |
| Product Type | Socket |

Configuration Features

| | |
|---------------------|-------------|
| Center Key | Offset Left |
| Number of Keys | 1 |
| Module Orientation | Right Angle |
| Number of Positions | 260 |
| Number of Rows | 2 |
| Keying | Standard |

Electrical Characteristics

| | |
|--------------|-------|
| DRAM Voltage | 1.2 V |
|--------------|-------|

Signal Characteristics



| | |
|---------------|-------|
| SGRAM Voltage | 1.2 V |
|---------------|-------|

Body Features

| | |
|-------------------------|--------------------------------|
| Ejector Location | Both Ends |
| Latch Material | High Temperature Thermoplastic |
| Retention Post Location | Both Ends |
| Module Key Type | Offset Left |
| Ejector Type | Locking |
| Connector Profile | Low |

Contact Features

| | |
|--|--|
| Socket Style | SO DIMM |
| PCB Contact Termination Area Plating Material | Gold Flash |
| Contact Base Material | Copper Alloy |
| Contact Mating Area Plating Material | Gold |
| Contact Mating Area Plating Material Thickness | .127 μm [5 μin] |
| Contact Current Rating (Max) | .5 A |
| Socket Type | Memory Card |

Termination Features

| | |
|-----------------|--------|
| Insertion Style | Cam-In |
|-----------------|--------|

Mechanical Attachment

| | |
|--------------------------|---------------|
| PCB Mount Retention | With |
| PCB Mount Retention Type | Solder Peg |
| PCB Mounting Style | Surface Mount |
| Connector Mounting Type | Board Mount |

Housing Features

| | |
|--------------------|--------------------------------|
| Centerline (Pitch) | .5 mm[.02 in] |
| Housing Color | Black |
| Housing Material | High Temperature Thermoplastic |

Dimensions

| | |
|--------------------|-----------------|
| Stack Height | 5.2 mm[.205 in] |
| Row-to-Row Spacing | 8.2 mm[.322 in] |

Usage Conditions

| | |
|-----------------------------|---|
| Operating Temperature Range | -55 – 85 $^{\circ}\text{C}$ [-67 – 185 $^{\circ}\text{F}$] |
|-----------------------------|---|



Operation/Application

Circuit Application

Power

Industry Standards

UL Flammability Rating

UL 94V-0

Packaging Features

Packaging Method

Tape & Reel

Packaging Quantity

800

Product Compliance

For compliance documentation, visit the product page on [TE.com](#)>

EU RoHS Directive 2011/65/EU

Compliant

EU ELV Directive 2000/53/EC

Compliant

China RoHS 2 Directive MIIT Order No 32, 2016

No Restricted Materials Above Threshold

EU REACH Regulation (EC) No. 1907/2006

Current ECHA Candidate List: JAN 2021 (211)
Candidate List Declared Against: JAN 2021 (211)
Does not contain REACH SVHC

Halogen Content

Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free

Solder Process Capability

Reflow solder capable to 260°C

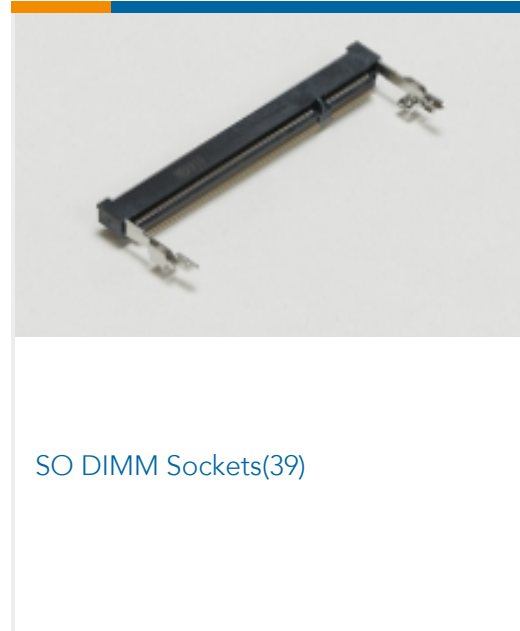
Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: <https://echa.europa.eu/guidance-documents/guidance-on-reach>

Compatible Parts



Also in the Series | DDR4 DIMM



Customers Also Bought





Documents

Product Drawings

[DDR4 SODIMM 260P 5.2H STD](#)

English

CAD Files

[3D PDF](#)

3D

Customer View Model

[ENG_CVM_CVM_2309409-2_1.2d_dxf.zip](#)

English

Customer View Model

[ENG_CVM_CVM_2309409-2_1.3d_igs.zip](#)

English

Customer View Model

[ENG_CVM_CVM_2309409-2_1.3d_stp.zip](#)

English

By downloading the CAD file I accept and agree to the [Terms and Conditions](#) of use.

Product Specifications

[Application Specification](#)

English